

Investor Presentation March 2018

**NASDAQ: ATOM** 

# Note Regarding Forward-Looking Statements



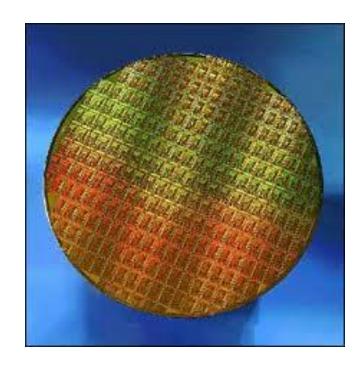
This presentation contains forward-looking statements concerning Atomera Incorporated (""Atomera," the "Company," "we," "us," and "our"). The words "believe," "may," "will," "potentially," "estimate," "continue," "anticipate," "intend," "could," "would," "project," "plan," "expect" and similar expressions that convey uncertainty of future events or outcomes are intended to identify forward-looking statements. These forward-looking statements are subject to a number of risks, uncertainties and assumptions, including those described in the "Risk Factors" section of our Annual Report on Form 10-K for the year ended December 31, 2017 filed with the SEC on March 6, 2018 (the "2017 Annual Report"). In light of these risks, uncertainties and assumptions, the forward-looking events and circumstances discussed in this presentation may not occur and actual results could differ materially and adversely from those anticipated or implied in our forward-looking statements. You should not rely upon forward-looking statements as predictions of future events. Although we believe that the expectations reflected in our forward-looking statements are reasonable, we cannot guarantee that the future results, levels of activity, performance or events and circumstances described in the forward-looking statements will be achieved or occur.

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### **Investment Overview**



- Mears Silicon Technology (MST®) is a semiconductor enhancement technology
  - Improves electron mobility resulting in higher performance, lower power, and lower costs
- Capital-light IP licensing business
  - Highly leverageable business model with strong cash position
  - Robust and growing patent portfolio to support licensing activities
  - Core R&D complete after \$80M and 15 years
- Currently engaged with 50% of world's top semiconductor makers
  - Total available market: \$4.0 B
- Strong team to commercialize technology
  - CEO ran \$1B+ divisions at Broadcom and Altera
  - Founder/CTO co-invented the erbium-doped fiber amplifier
- NASDAQ Ticker: "ATOM" IPO in August 2016



## **Extending Moore's Law**



#### The skyrocketing cost of new nodes



Source: McKinsey & Co, "On Semiconductors"

MST: A way out

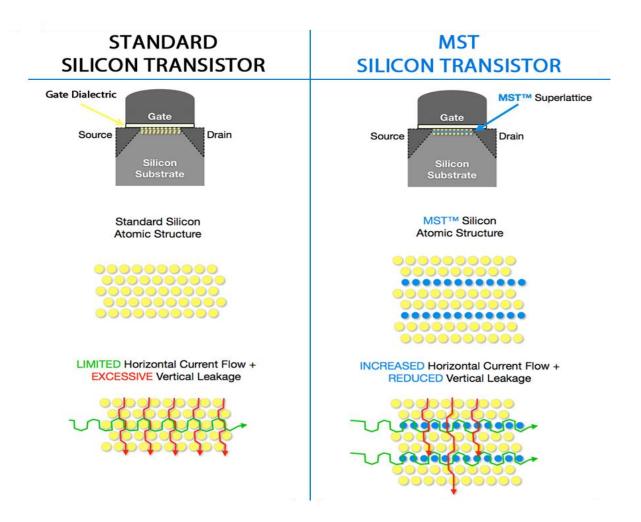
- MST can deliver a half to a full node of benefits.
  - Extends life of depreciated fabs
  - Continues reducing the cost per transistor
  - May solve problems in geometries smaller than 28 nm
- MST cost is tiny in comparison to developing a new node
  - Process development/licensing is ~\$10M
  - Foundry equipment upgrades cost is ~\$30-50M
  - A foundry for a new node costs billions

### "From an economic standpoint, Moore's law is over."

Silicon Valley analyst Lynley Gwynnap, quoted in "After Moore's Law," *The Economist*, 12 March 2016

# MST Technology





#### **Potential Benefits**

- Improved Efficiency
  - Improved performance
  - Lower power consumption
  - Some combination of the two
- Reduced Die Size
  - Lower power needs
  - Lower bottom line cost
- Improved Yield
  - Less waste
  - Easier design parameters

### **Potential Benefits**



- Overall Improved Efficiency: Smartphone
  - 45%-52% added battery life (depending on usage)
  - Increased cost to add MST expected to be insignificant to total phone cost
  - Opportunity to increase performance instead of saving power
- Reduced Die Size: Power Management Integrated Circuit (IC)
  - Die size reduction of 15-21%
  - Would result in lower power draw
  - Would also reduce total cost per device
- Product Enablement: Mobile Double Data Rate (DDR) Memory
  - Could create a whole new class of memory for mobile devices
  - Would enable low-power wearables and Internet-of-Things devices
  - May provide significant improvements to standby power





### Semiconductor Ecosystem



Process Development

Wafer Fabrication

Chip Makers / Sellers

Equipment Manufacturers

**Foundries** 

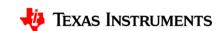






Integrated Device Manufacturers (IDM)







Fabless



Vertically Integrated Firms





**Supporting Ecosystem** 

Semiconductor Equipment Manufacturers







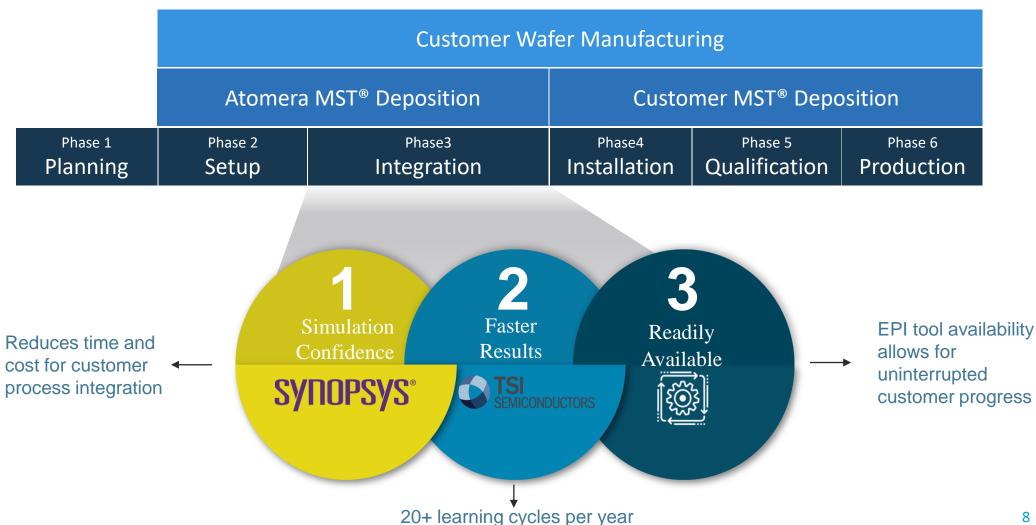
**Electronic Design Automation Tools** 





### Accelerating time to license





# Largest Companies with fabs



	Company	Туре	Market Segment	Total Capacity - Wf/mon. (200mm equ)
1	Samsung Semiconductor	IDM	Memory	2,598,750
2	TSMC	Foundry	Logic	2,012,317
3	Micron Technology	IDM	Memory	1,540,500
4	SK Hynix	Foundry	Memory	1,530,000
5	Toshiba Semiconductor	IDM	Memory	1,158,750
6	GlobalFoundries	Foundry	Logic	810,000
7	Intel	IDM	MCU	681,750
8	Texas Instruments (TI)	IDM	Analog	620,879
9	UMC (United Microelectronics)	Foundry	Logic	614,863
10	STMicroelectronics	IDM	Analog	461,006
11	SMIC	Foundry	Logic	432,750
12	Infineon Technologies	IDM	Analog	375,809
13	ON Semiconductor	IDM	Analog	374,492
14	Powerchip Technology	Foundry	Logic	313,000
15	TowerJazz	Foundry	Analog	297,735
16	NXP Semiconductors	IDM	Analog	250,000
17	Renesas Electronics	IDM	Other	236,124
18	Japan Semiconductor Corp. (Toshiba)	Foundry	Analog	229,944
19	Huahong Grace Semiconductor (HHGrace)	Foundry	Analog	213,000
20	IM Flash	IDM	Memory	180,000
21	Vanguard International Semiconductor (VIS)	Foundry	Analog	175,000
22	MagnaChip Semiconductor	Foundry	Analog	155,000
23	Nanya Technology	IDM	Memory	135,000
24	Fujitsu Semiconductor	IDM	Logic	131,728
25	China Resources Microelectronics (CR Micro)	IDM	Analog	130,846

- Total industry capacity 17.8M wafers/month
- Top 25 wafer capacity leaders
  - 89% of total industry capacity at end of 2016

Source: IC Insights Global Wafer Capacity 2017-2021 report

# **Atomera Business Opportunity**



### **License Fees**

### **Engineering Service Fees**

### Royalties

Example 1. Worldwide Averag	ge Fab¹
Monthly Fab Capacity (wafers/month)	40,000
Wafer ASP	\$1,637
Annual Revenue Potential <sup>2</sup>	\$7.9M

Example 2. Leading Foundry, 40nm Fab					
Monthly Fab Capacity (wafers/month)	80,000				
Wafer ASP	\$3,000				
Annual Revenue Potential <sup>2</sup>	\$28.8M				

<sup>1. 2016: 375</sup> fabs worldwide with a total of 15.2M wafers per month

<sup>2.</sup> Assumes 50% penetration Sources: IC Insights

# Market Segment Strategy



### **Leading Analog**

Analog, PMIC, RF

Big Players: TSMC, TI, NXP, ST Micro

#### **Challenges**

Difficult to find new options for cost, performance, power improvements

#### Atomera solutions

MST can lower die cost while improving other parameters

### Mainstream

IoT, RF, Automotive

Big Players: TSMC, UMC, SMIC, Global Foundries

#### Challenges

Many fully depreciated factories need a performance boost to remain competitive

#### Atomera solutions

MST allows fab life extension by upping performance within node

### **Leading Planar**

DRAM; Digital Processors

Big Players: TSMC, GF, Samsung, Hynix, Micron

#### Challenges

Alternatives to planar transistors are both expensive and can affect product performance

#### **Atomera solutions**

MST provides a low cost alternative to extend planar life

#### **3D**

FinFET, Nanowire

Big Players: Intel, TSMC, Samsung, GF

#### Challenges

FinFET cost, variability, manufacturability. Looking at exotic material solutions

#### Atomera solutions

MST is a low risk, silicon based technology with multiple benefits

180nm

130nm

90nm

65nm

40nm

28nm

16nm

14nm

10nm

.

7nm 5n

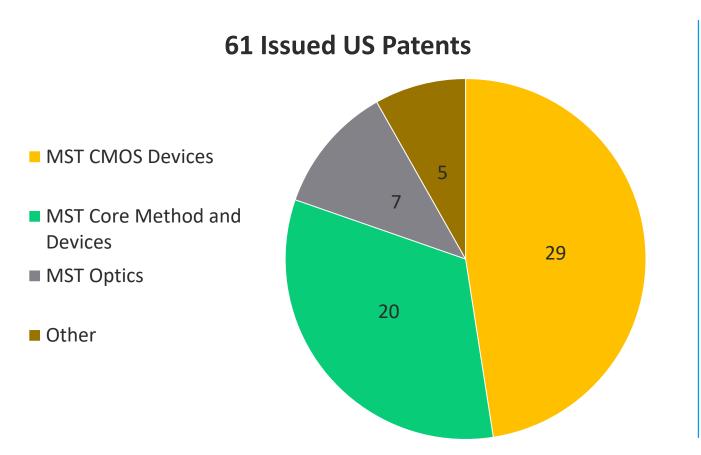
5nm

Now engaged with customers in all four segments

### Patent Portfolio



### 22 New US Patents Applications Filed in 2017



- Strong Patent Portfolio
  - Covers core elements of MST
  - Constantly adding new patents
- Discoverable and enforceable
  - Infringement can be easily discovered using electron microscopy
- International Strategy
  - Including foreign counterparts, portfolio
     has over 110 granted patents

### **Financials**



			2017				2016
	FY 2017	FY 2016	Q4 2017	Q3 2017	Q2 2017	Q1 2017	Q2 2016
<b>GAAP Results</b>							
Revenue	\$0.1M	-	\$0.1M	-	-	-	-
Gross Profit	\$0.1M	-	\$0.1M	-	-	-	100
Operating Expense	(\$13.3M)	(\$10.0M)	(\$2.7M)	(\$3.3M)	(\$3.7M)	(\$3.6M)	(\$1.9M)
Net Loss	(\$13.1M)	(\$12.6M)	(\$2.6M)	(\$3.3M)	(\$3.6M)	(\$3.5M)	(\$2.6M)
Loss Per Share	(\$1.08)	(\$2.22)	(\$0.21)	(\$0.27)	(\$0.30)	(\$0.29)	(\$1.61)
Reconciliation between GAAP & Non-GAAP*							
Net Loss (GAAP)	(\$13.1M)	(\$12.6M)	(\$2.6M)	(\$3.3M)	(\$3.6M)	(\$3.5M)	(\$2.6M)
Interest Expense		\$2.6M					
Stock-Based Compensation	\$4.0M	\$2.5M	(\$0.5M)	(\$0.9M)	(\$1.4M)	(\$1.2M)	(\$0.1M)
Adjusted EBITDA (Non-GAAP)*	(\$9.1M)	(\$7.5M)	(\$2.1M)	(\$2.4M)	(\$2.2M)	(\$2.4M)	(\$1.8M)
Cash at December 31, 2017	\$17.4M						
Shares Outstanding at December 31, 2017	12.2M						

<sup>\*</sup> For a full reconciliation of GAAP and non-GAAP results, please see our press release issued February 13, 2018.

## Summary



- High margin, recurring revenue financial model
- Well funded with strong cash position
- Solid progress with initial customers in pipeline
- Strong technology and patent position
- Experienced management team to execute business plan



# What's New

March 2018

### What's new – March 2018

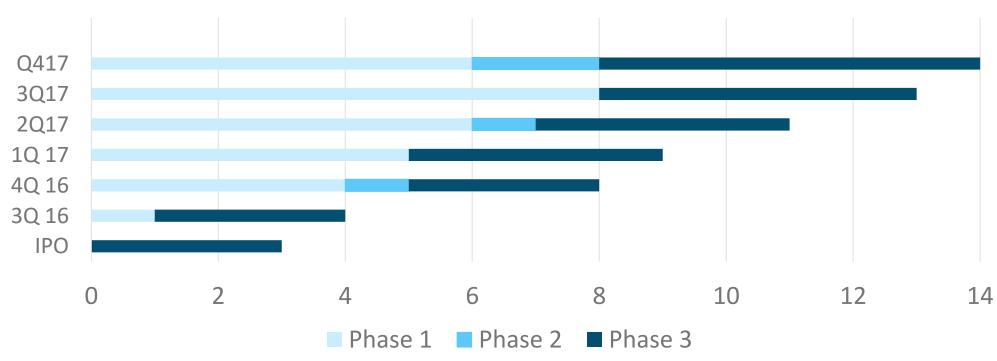


- Achieved first engineering service revenue of \$110K in Q4
- Now engaged with 14 customers, 6/2/6 in the three phases
- Working with customers in unexpected ways
  - Skipping directly into phase 3
  - Considering licensing after phase one
  - Installation prior to license execution
- Installation of MST in a factory has commenced with one customer
  - Under evaluation license terms
- TCAD modeling revolutionizing customer evaluations/integration

# **Customer Pipeline**





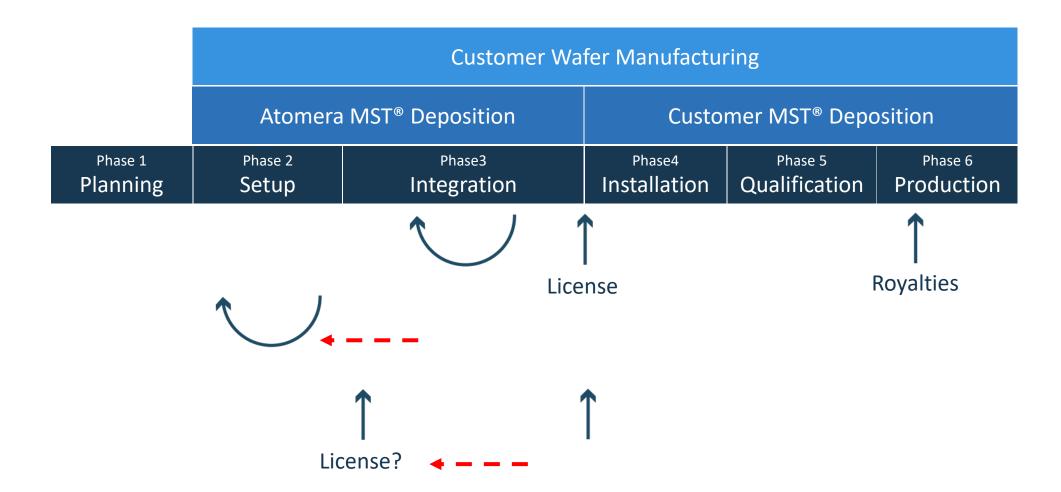


Now engaged with 50% of the world's top semiconductor makers\*

<sup>\* 10</sup> of the top 20 (IC Insights, McClean Report 2017)

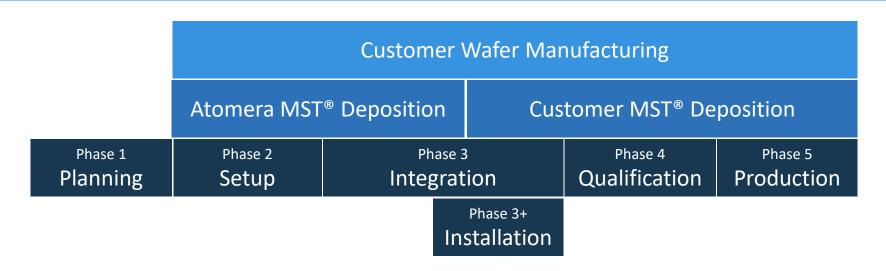
## **Customer Engagement Changes**





## Early Installation Advantages



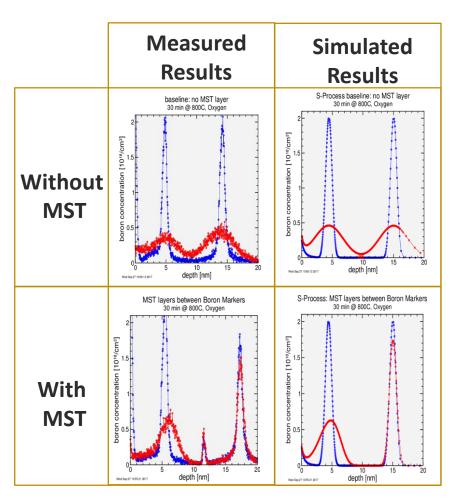


- Significantly lowers cost of processing test wafers
- Speeds throughput by avoiding shipping/contamination/calibration time
- Improves capacity both for Epi tools and our engineers
- Raises our stature within Epi OEMs
- Customer Epi engineers become an internal advocate for multiple process nodes

### TCAD Modelling Advantage



- TCAD allows customers simulate MST quickly and inexpensively
- Engages customers earlier to understand how to use
   MST
  - Benefits
  - Best integration techniques
- Frequently causes more ownership on customer side
- Builds early credibility and desire to experiment
  - Early license discussions
  - Horizontal buy-in at customer

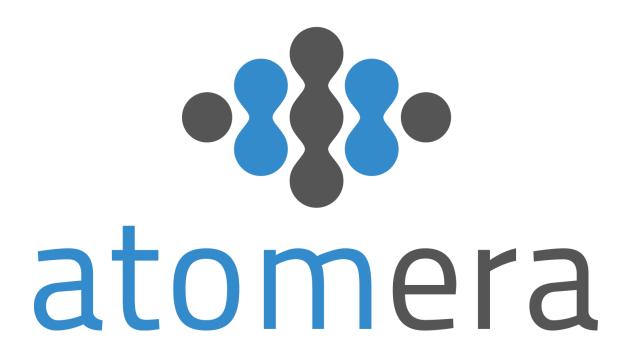


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